

What is claimed is:

1. An IC card, comprising:
 - a first support;
 - a second support;
 - an IC module including an IC chip, a reinforcing structural member neighboring to the IC chip and an antenna; the IC module provided between the first and second supports;
 - a first adhesive layer provided between the first support and the reinforcing structural member; and
 - a second adhesive layer provided between the second support and the IC chip;

wherein when the IC card is curved with a radius R1 of curvature, the following formula is satisfied:

$$R1 < R1' < R2 \leq R3$$

where $R1'$ is a radius of curvature of an outermost layer of the IC card, $R2$ is a radius of curvature of the reinforcing structural member, and $R3$ is a radius of curvature of the IC chip.
2. The IC card of claim 1, wherein when $D1$ is a thickness of the first adhesive layer and $T1$ is the maximum length of the reinforcing structural member, $D1/T1$ is 0.001 to 0.05.

3. The IC card of claim 2, wherein D1/T1 is 0.002 to 0.04.

4. The IC card of claim 1, wherein the reinforcing structural member is a metallic reinforcing plate having an upper surface on which the IC chip is mounted and the area of the upper surface of the metallic reinforcing plate is larger than the area of the IC chip, and

wherein when θ is an angle between the upper surface of the metallic reinforcing plate and a line connecting an edge of the upper surface of the metallic reinforcing plate with an edge of an upper surface of the IC chip, the following formula is satisfied:

$$0.02 < \tan \theta < 0.2$$

5. The IC card of claim 4, wherein the following formula is satisfied:

$$0.03 < \tan \theta < 0.15$$

6. The IC card of claim 1, wherein when D2 is a thickness of the second adhesive layer and T1 is the maximum length of the reinforcing structural member, D2/T1 is 0.001 to 0.05.

7. The IC card of claim 6, wherein D2/T1 is 0.002 to 0.04.

8. The IC card of claim 1, wherein the first and second adhesive layers have a 2% modulus of elasticity of 5 kg/mm² to 55 kg/mm² and a ductility at a breaking point of 200% to 1300%.

9. The IC card of claim 8, wherein the 2% modulus of elasticity is 6 kg/mm² to 50 kg/mm².

10. The IC card of claim 1, wherein the reinforcing structural member has a Young's modulus of 150 Gpa to 450 Gpa.

11. The IC card of claim 1, wherein the IC card has a thickness of 5 μ m to 100 μ m.

12. The IC card of claim 1, wherein an image receiving layer is provided on the first support.

13. The IC card of claim 1, wherein and a writable layer is provided on the second support.

14. The IC card of claim 1, wherein the first and second adhesive layer is formed by a reactive-type hot-melt adhesive.